

ABSTRACT OF THE DISCLOSURE

Stereolithographic methods for fabricating conductive elements and for bonding conductive elements to contacts of semiconductor device components. The conductive elements may include forming multiple superimposed, contiguous, mutually adhered layers of a conductive material, such as a thermoplastic conductive elastomer or a metal. The conductive elements may alternatively comprise conductive traces or vias of circuit boards or interposers. A machine vision system may be used to recognize the position, orientation, and features of a semiconductor device assembly, semiconductor die, or other substrate to control stereolithographic application of material thereto.